



Announcement

Dated 13 April, 2006

The Board of Directors of **IRIS Corporation Berhad (ICB)** is pleased to announce that the company has signed a cross-license and business agreement with **Smart Packaging Solutions (SPS)**, a company incorporated and domiciled in France.

SPS provides manufacturing technology and expertise to manufacture micropackaging and microelectronic systems including contact and contactless smart cards and devices dedicated to identity and security markets using ID cards and passports.

The agreement provides for the sharing of each company's technologies and resources. Specifically, it was also agreed that **ICB** would promote **SPS's technologies** in the Asian and American Continents and in return **SPS** would promote **ICB's technologies** in the European Continent

Under the terms of the agreement, **ICB** would be the second source E-Pastilles modules supplier for **SPS's Id projects** and **SPS** will provide E-Pastilles modules for **ICB's Id projects** that would incorporate **ICB and SPS technologies**.

The agreement also covers the exclusive supply of transfer molding contactless modules to **SPS** for their special markets.

The Board is confident that this cooperation between the two companies is expected to create more opportunities and open up new markets for **ICB** especially in the Europe region.

The directors, substantial shareholders or persons connected or associated with them have no personal interest in this agreement.

Smart Packaging Solutions

S.A.S. au capital de 620 119 € RC Aix

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